



## Glass Passivated Bridge Rectifiers

### Features

- Glass passivated chip
- Low forward voltage drop
- Ideal for printed circuit board
- High surge current capability

### Mechanical Data

- Polarity: Symbol marked on body
- Mounting position: Any

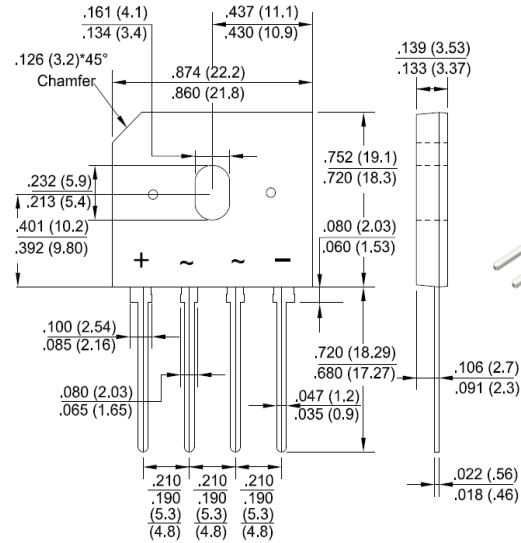
Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

### Applications

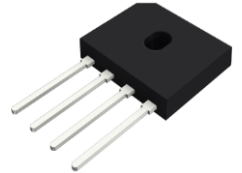
- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.

**Reverse Voltage - 50 to 1000 Volts**  
**Forward Current - 4.0 Amperes**

### GBU



RoHS COMPLIANT



## Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristics	Symbol	GBU4005	GBU401	GBU402	GBU404	GBU406	GBU408	GBU410	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum Average Forward (with heatsink Note 2) Rectified Current @ T <sub>c</sub> =100°C (without heatsink)	I <sub>(AV)</sub>					4.0			A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>					150			A
I <sup>2</sup> t Rating for Fusing (t<8.3mS)	I <sup>2</sup> t					93.4			A <sup>2</sup> s
Peak Forward Voltage Per Diode at 2A DC	V <sub>F</sub>					0.95			V
Peak Forward Voltage per Diode at 4A DC	V <sub>F</sub>					1.05			V
Maximum DC Reverse Current at Rated @T <sub>J</sub> =25°C	I <sub>R</sub>					5.0			μA
DC Blocking Voltage per Diode @T <sub>J</sub> =125°C						500			
Typical Junction Capacitance Per Diode (Note1)	C <sub>J</sub>					45			pF
Typical Thermal Resistance to Ambient (without heatsink)	R <sub>θJA</sub>					27			°C/W
Typical Thermal Resistance to case (with heatsink (Note2) )	R <sub>θJC</sub>					2.2			°C/W
Typical Thermal Resistance to lead (without heatsink)	R <sub>θJL</sub>					4.5			°C/W
Operating Junction Temperature Range	T <sub>J</sub>					-55 to +150			°C
Storage Temperature Range	T <sub>STG</sub>					-55 to +150			°C

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

2.Device mounted on 50mm\*50mm\*1.6mm Cu plate heatsink.

3.The typical data above is for reference only



Fig. 1 - Forward Current Derating Curve

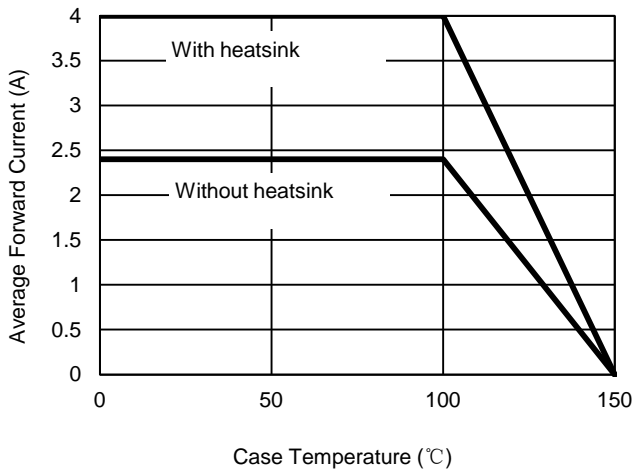


Fig. 2 - Maximum Non-Repetitive Surge Current

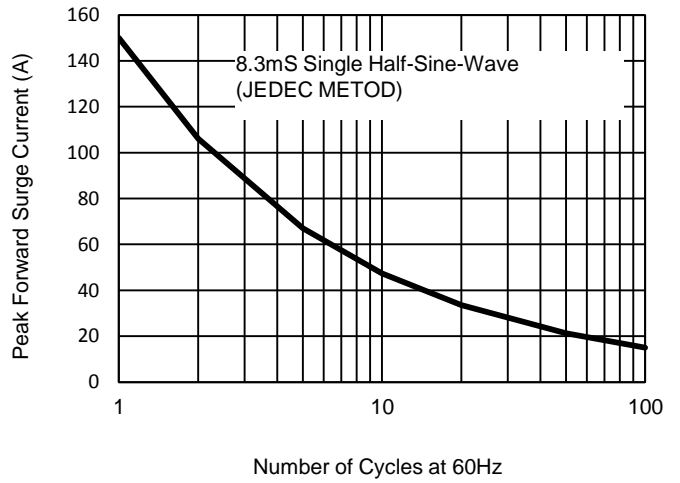


Fig. 3 - Typical Reverse Characteristics

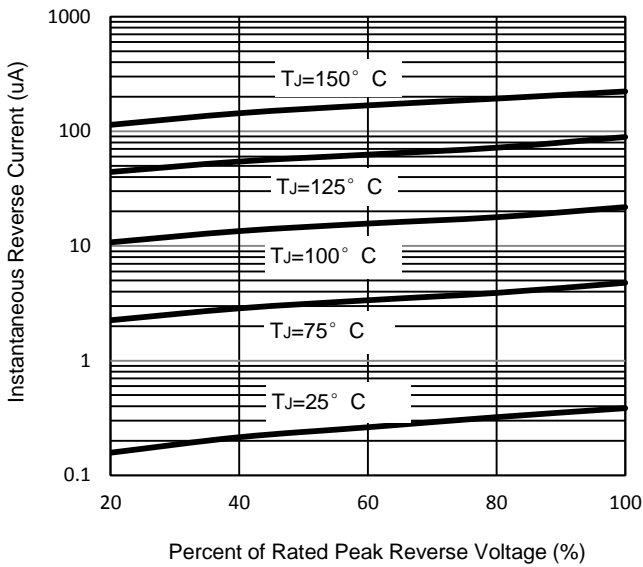


Fig. 4 - Typical Forward Characteristics

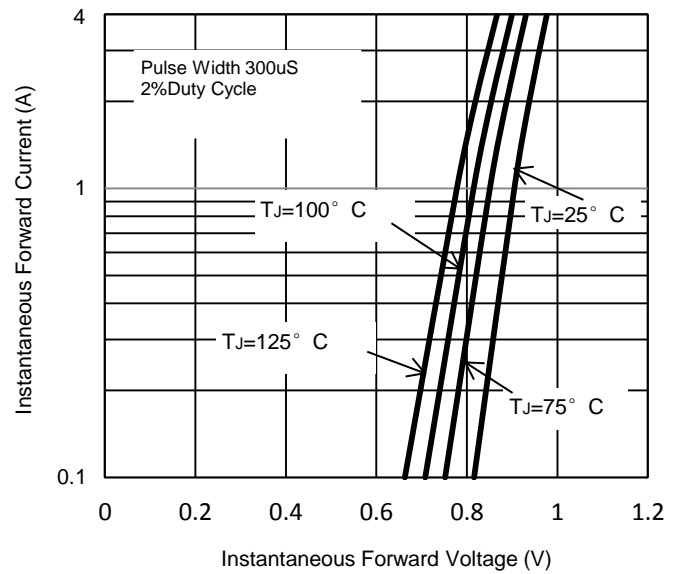
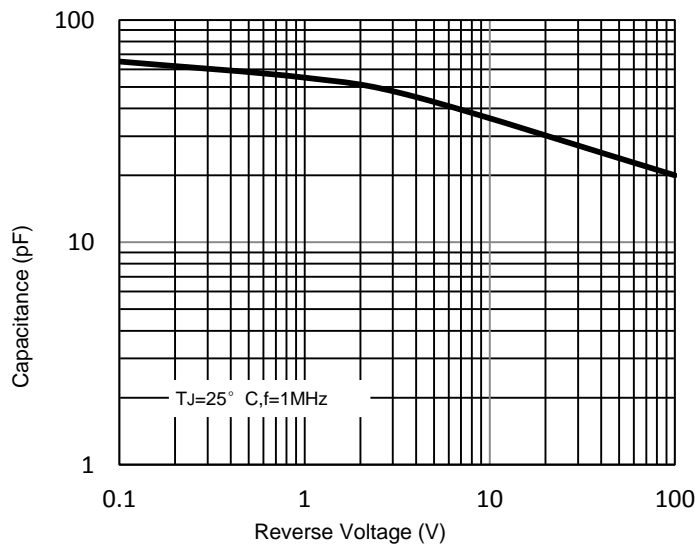


Fig. 5 - Typical Junction Capacitance



The curve above is for reference only.



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